1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	55	V
V_{GS}	Gate-source voltage	±20	V
I_D(1)	Drain current (continuous) at T_C = 25 °C	80	A
	Drain current (continuous) at T_C = 100 °C	80	A
I_{DM}(2)	Drain current (pulsed)	320	A
P_{TOT}	Total dissipation at T_C = 25 °C	300	W
P_1	Long term load test (I_D= 100 A, V_{DS}= 1.5 V, t_{pulse}=10 ms) ΔV_{SD} (tested)	150	W
P_2 (3)	Short term load test (I_D= 75 A, V_{DS}= 15 V, t_{pulse}=700 µs) ΔV_{SD} (not tested)	1125	W
E_{AS}(4)	Single-pulse avalanche energy	1.3	J
dv/dt(5)	Peak diode recovery voltage slope	7	V/ns
T_{stg}	Storage temperature range	-55 to 175	°C
T_j	Operating junction temperature range		

1. *Current limited by package.*
2. *Pulse width limited by safe operating area.*
3. *Defined by design, not subject to production test.*
4. *Starting T_J = 25 °C, I_D = 30 A, V_{DD} = 30 V*
5. *I_{SD} ≤ 80 A, di/dt ≤ 300 A/µs, V_{DD} ≤ $V_{(BR)DSS}$, T_J ≤ T_{JMAX}*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	0.5	°C/W
$R_{thj\text{-}pcb}$(1)	Thermal resistance junction-pcb	35	°C/W

1. *When mounted on an FR-4 board of 1 inch², 2 oz Cu.*

2 Electrical characteristics

T_{CASE} = 25 °C unless otherwise specified

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 250 µA	55			V
V_{BR0}		V_{GS}= 1.5 V, I_D = 250 µA	40			V
V_{BR1}		V_{GS}= 1.5 V, I_D = 10 mA	40			V
V_{BR2}		V_{GS}= 1.5 V, I_D = 100 mA	40			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 55 V			10	µA
		V_{GS} = 0 V, V_{DS}= 55 V T_C = 125 °C (1)			100	µA
I_{GSS} (2)	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2		4	V
		V_{DS} = V_{GS} I_D = 1 mA, T_j=175 °C (1)	1			V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 40 A		5.0	6.5	mΩ

1. *Defined by design, not subject to production test.*
2. *Tested @V_{GS}= ±22 V at wafer level.*

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	4400		pF
C_{oss}	Output capacitance		-	1020		pF
C_{rss}	Reverse transfer capacitance		-	350		pF
Q_g	Total gate charge	V_{DD} = 27.5 V, I_D = 80 A, V_{GS} = 0 to 10 V (see Figure 13. Test circuit for gate charge behavior)	-	142	193	nC
Q_{gs}	Gate-source charge		-	29		nC
Q_{gd}	Gate-drain charge		-	60.5		nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 27 V, I_D = 40 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	27	-	ns
t_r	Rise time		-	155	-	ns
$t_{d(off)}$	Turn-off delay time		-	125	-	ns
t_f	Fall time		-	65	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		80	A
I_{SDM}(1)	Source-drain current (pulsed)		-		320	A
V_{SD}(2)	Forward on voltage	I_{SD} = 80 A, V_{GS} = 0 V	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 80 A, di/dt = 100 A/µs, V_{DD} = 35 V, T_J = 150 °C (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	100		ns
Q_{rr}	Reverse recovery charge		-	325		nC
I_{RRM}	Reverse recovery current		-	6.5		A

1. *Pulse width limited by safe operating area*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

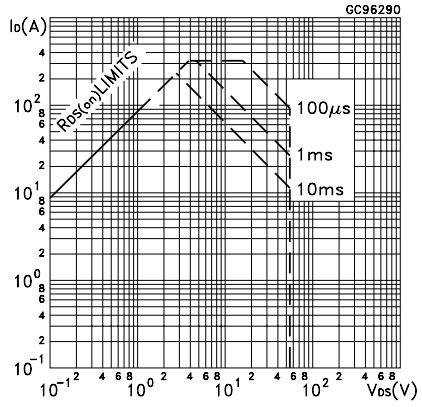


Figure 2. Thermal impedance

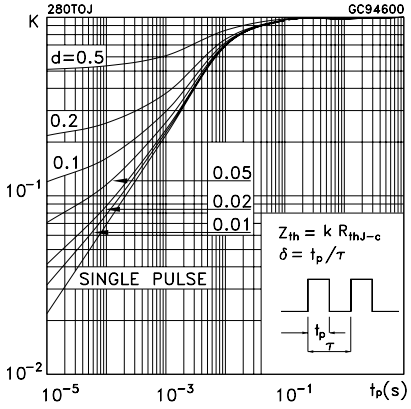


Figure 3. Output characteristics

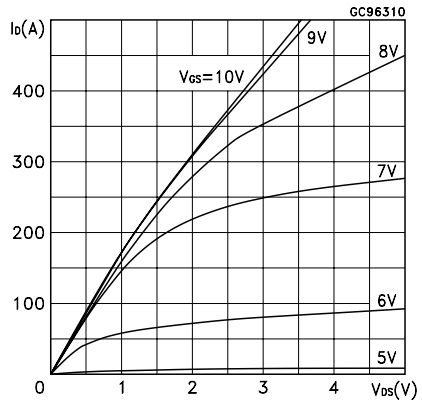


Figure 4. Transfer characteristics

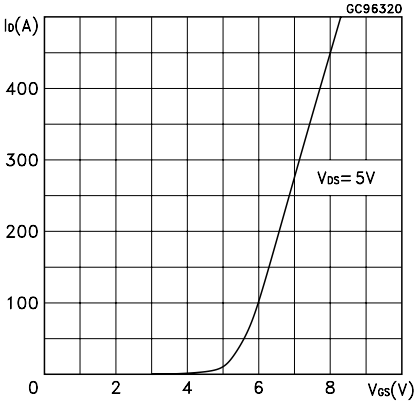


Figure 5. Static drain-source on-resistance

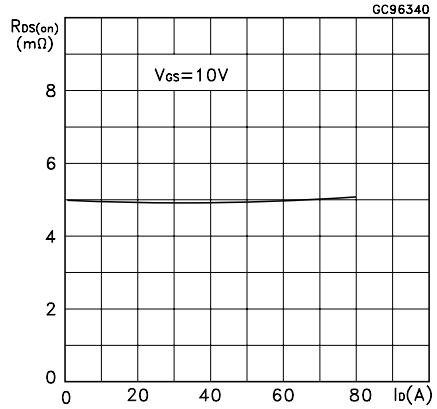


Figure 6. Gate charge vs gate-source voltage

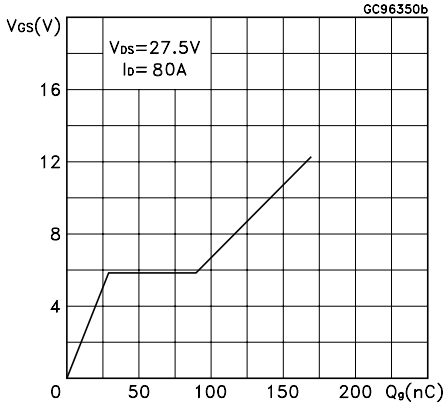


Figure 7. Capacitance variations

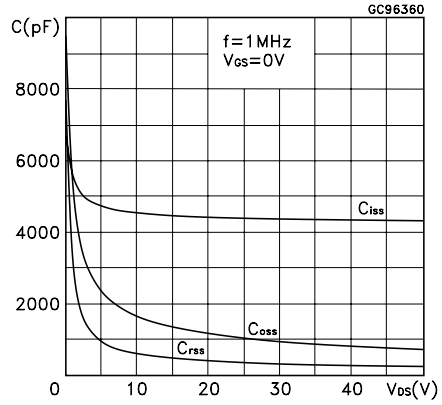


Figure 8. Normalized gate threshold voltage vs temperature

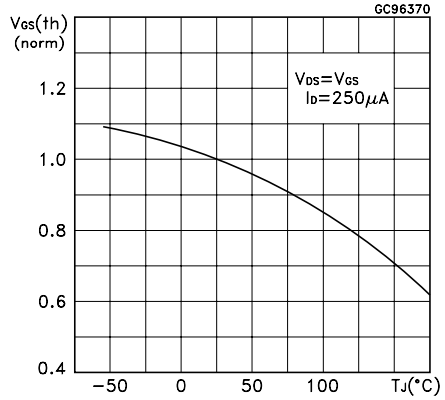


Figure 9. Normalized on-resistance vs temperature

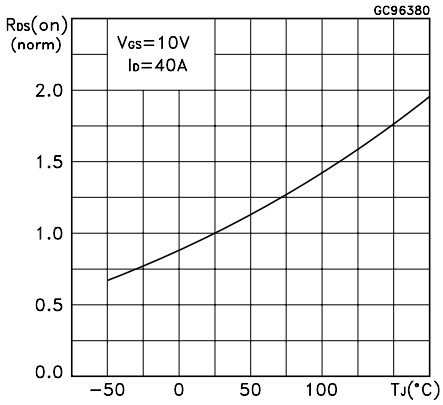


Figure 10. Source-drain diode forward characteristics

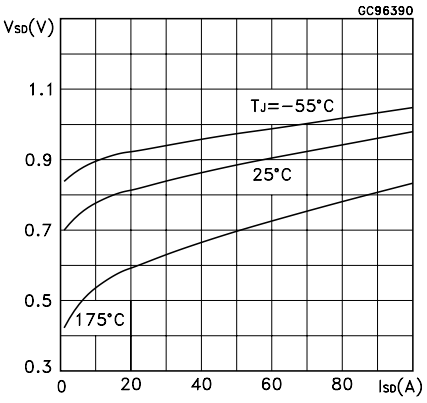
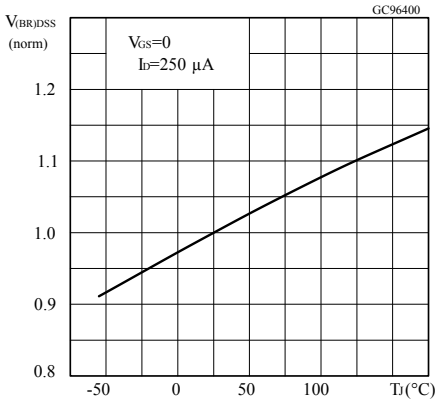


Figure 11. Normalized $V_{(BR)DSS}$ vs temperature



3 Test circuits

Figure 12. Test circuit for resistive load switching times

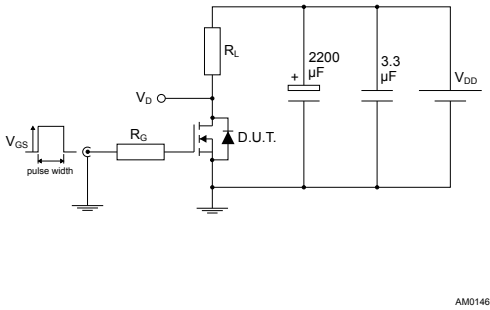


Figure 13. Test circuit for gate charge behavior

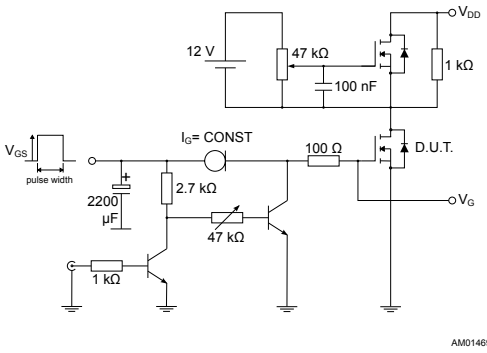


Figure 14. Test circuit for inductive load switching and diode recovery times

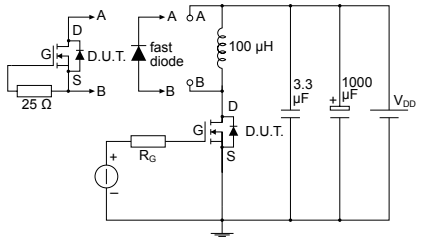


Figure 15. Unclamped inductive load test circuit

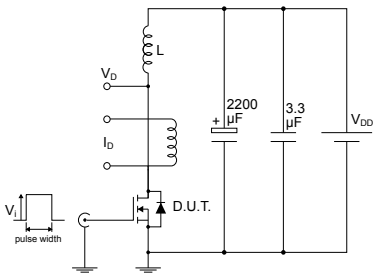


Figure 16. Unclamped inductive waveform

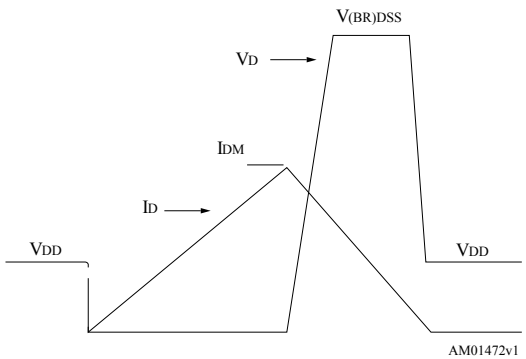
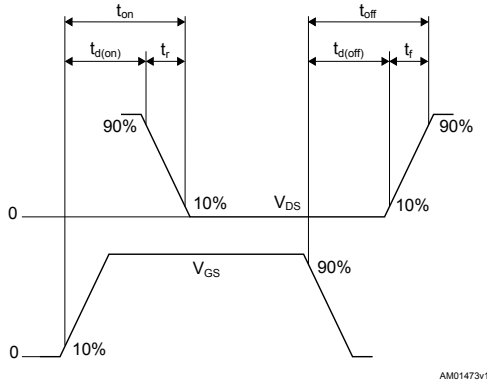


Figure 17. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 D²PAK (TO-263) type A package information

Figure 18. D²PAK (TO-263) type A package outline

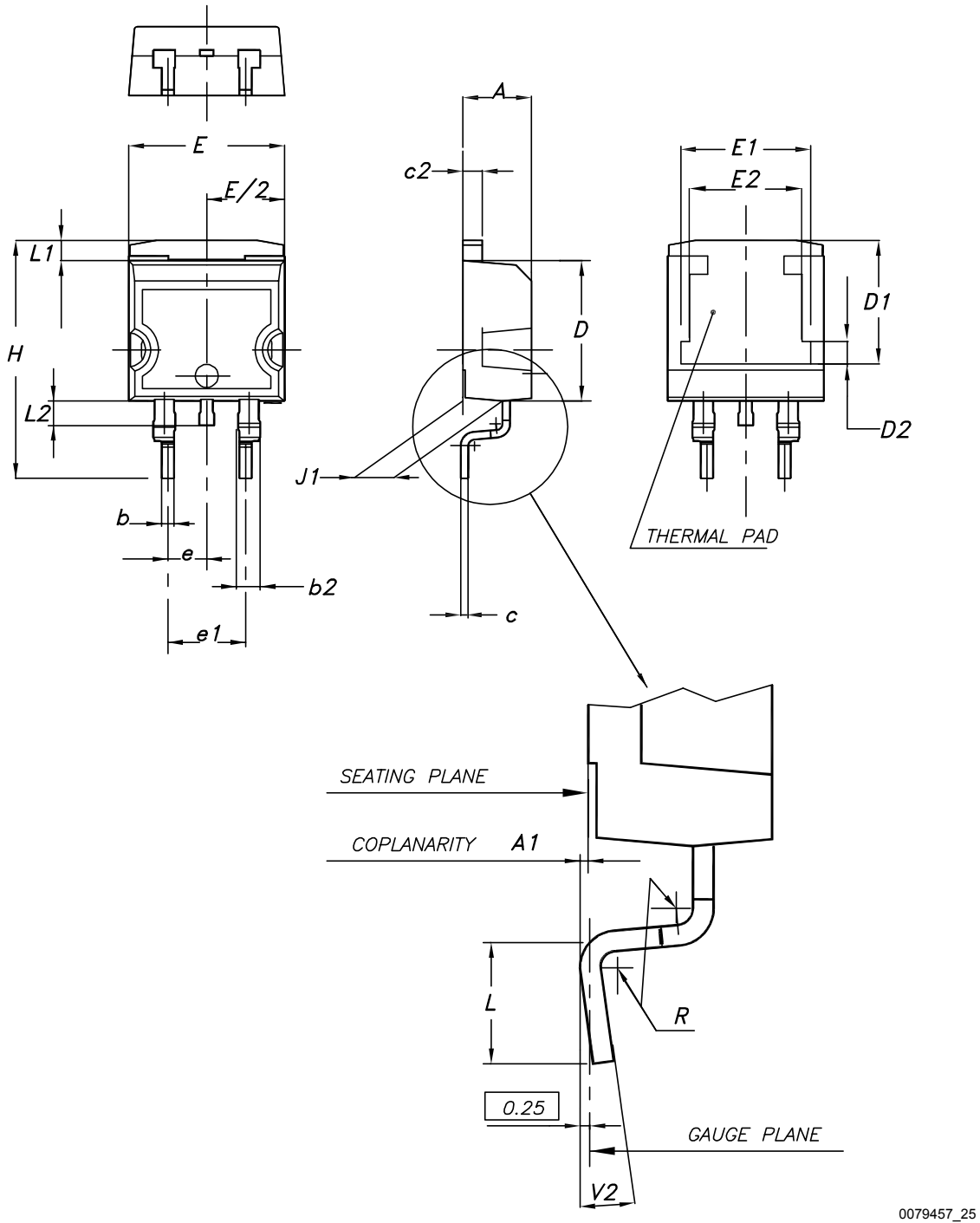
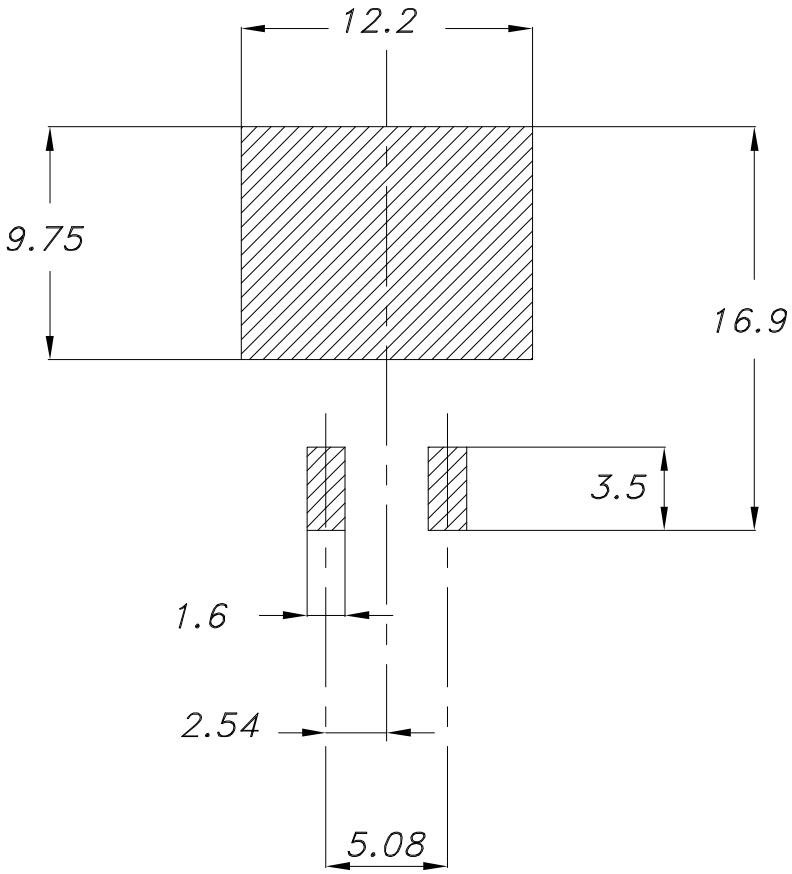


Table 7. D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 19. D²PAK (TO-263) recommended footprint (dimensions are in mm)



Footprint

4.2 D²PAK packing information

Figure 20. D²PAK tape outline

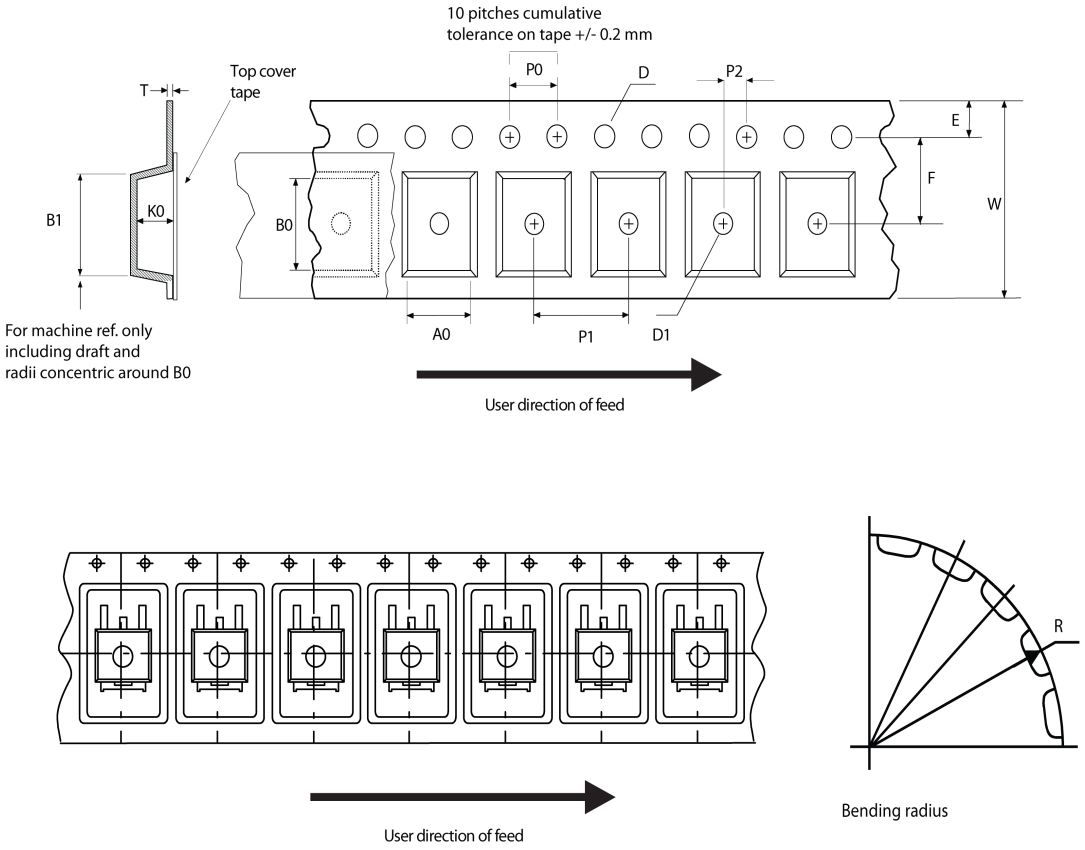
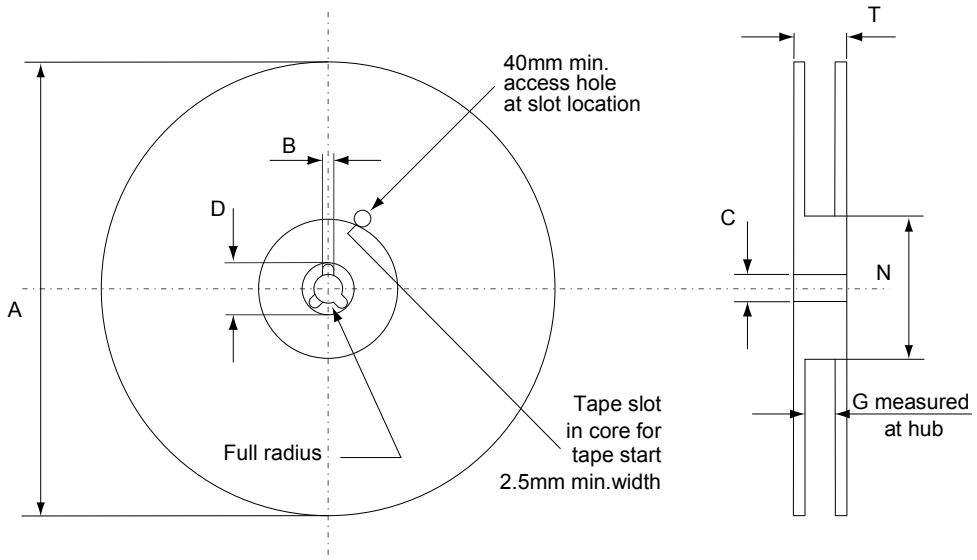


Figure 21. **D²PAK reel outline**



AM06038v1

Table 8. **D²PAK tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Revision history

Table 9. **Document revision history**

Date	Version	Changes
19-Jan-2012	1	First issue.
04-Sep-2018	2	Removed maturity status indication from cover page. The document status is production data. Modified Table 1. Absolute maximum ratings. Updated Section 4 Package information. Minor text changes.

Contents